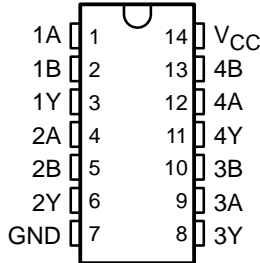
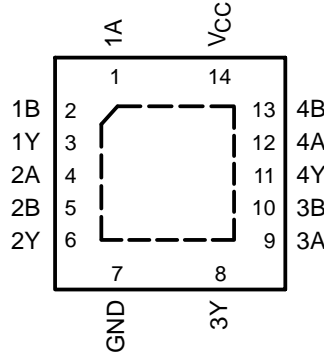


- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

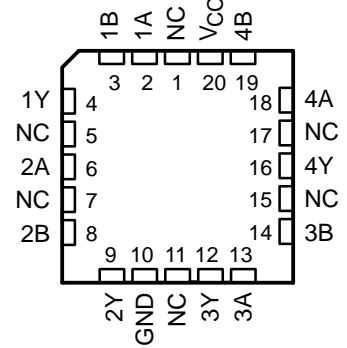
SN54AHCT00 . . . J OR W PACKAGE
SN74AHCT00 . . . D, DB, DGV, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74AHCT00 . . . RGY PACKAGE
(TOP VIEW)



SN54AHCT00 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'AHCT00 devices perform the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AHCT00RGYR	HB00
	PDIP – N	Tube	SN74AHCT00N	SN74AHCT00N
	SOIC – D	Tube	SN74AHCT00D	AHCT00
		Tape and reel	SN74AHCT00DR	
	SOP – NS	Tape and reel	SN74AHCT00NSR	AHCT00
	SSOP – DB	Tape and reel	SN74AHCT00DBR	HB00
	TSSOP – PW	Tube	SN74AHCT00PW	HB00
Tape and reel		SN74AHCT00PWR		
TVSOP – DGV	Tape and reel	SN74AHCT00DGV	HB00	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT00J	SNJ54AHCT00J
	CFP – W	Tube	SNJ54AHCT00W	SNJ54AHCT00W
	LCCC – FK	Tube	SNJ54AHCT00FK	SNJ54AHCT00FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SCLS229K – OCTOBER 1995 – REVISED JULY 2003

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
(see Note 2): DB package	96°C/W
(see Note 2): DGV package	127°C/W
(see Note 2): N package	80°C/W
(see Note 2): NS package	76°C/W
(see Note 2): PW package	113°C/W
(see Note 3): RGY package	47°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.



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SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

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recommended operating conditions (see Note 4)

		SN54AHCT00		SN74AHCT00		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-8		-8	mA
I _{OL}	Low-level output current		8		8	mA
Δt/Δv	Input transition rise or fall rate		20		20	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT00		SN74AHCT00		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1			0.1	V	
	I _{OL} = 8 mA				0.36		0.44	0.44		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*	±1	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2		20	20	μA	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		2	10			10	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT00		SN74AHCT00		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	5**	6.9**		1**	8**	1	8	ns
t _{PHL}				5**	6.9**		1**	8**	1	8	
t _{PLH}	A or B	Y	C _L = 50 pF	5.5	7.9		1	9	1	9	ns
t _{PHL}				5.5	7.9		1	9	1	9	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SCLS229K – OCTOBER 1995 – REVISED JULY 2003

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 5)

PARAMETER	SN74AHCT00			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.4	0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		-0.4	-0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		4.5		V
$V_{IH(D)}$ High-level dynamic input voltage	2			V
$V_{IL(D)}$ Low-level dynamic input voltage			0.8	V

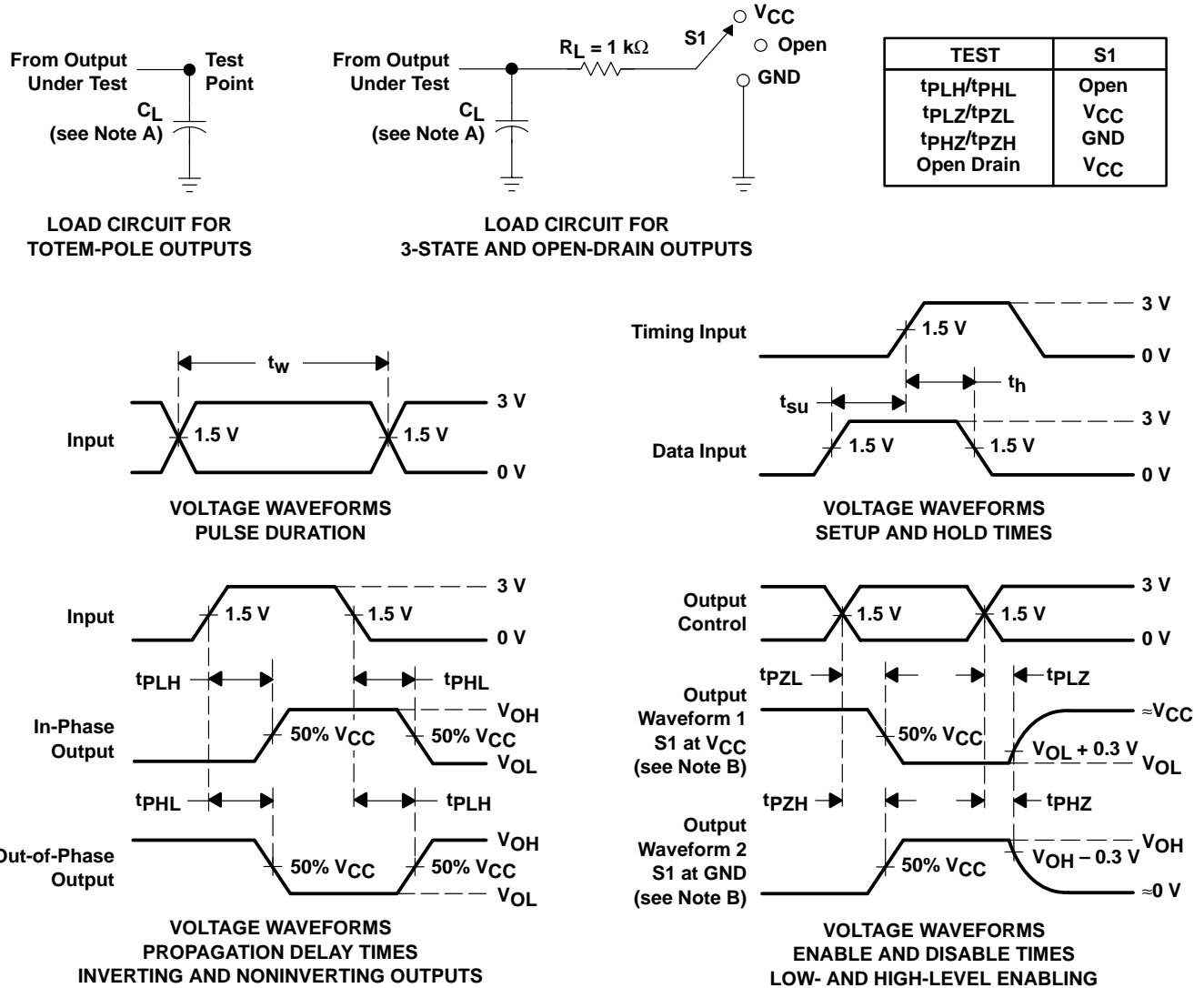
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	10.5	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9682301Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9682301QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9682301QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN74AHCT00D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74AHCT00DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT00NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT00NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AHCT00PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT00RGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74AHCT00RGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SNJ54AHCT00FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHCT00J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHCT00W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

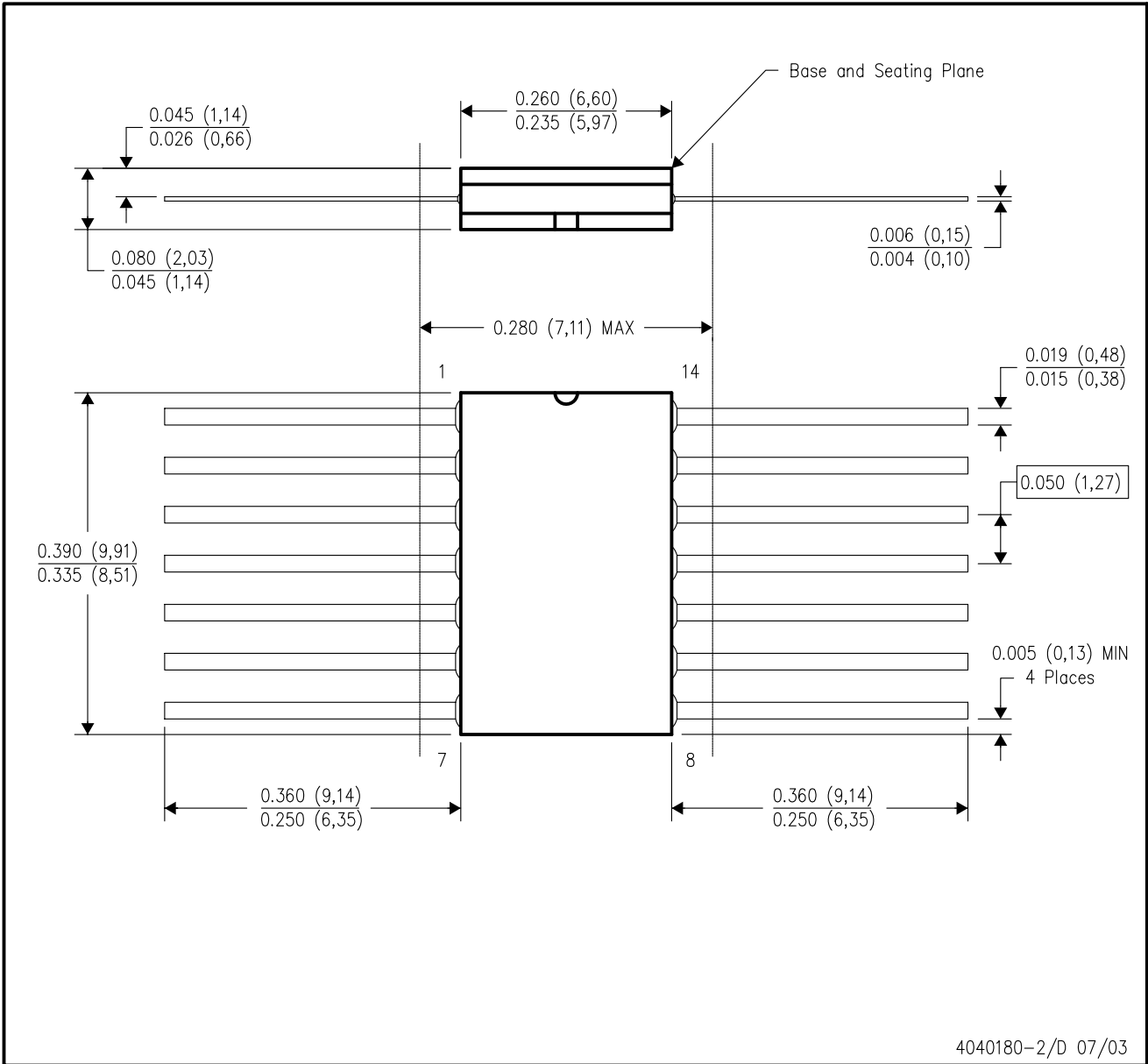


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE





- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AB.

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance.
 -  Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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